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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814
Examiner: Phat X. Cao

In re PATENT APPLICATION of:

Applicant(s): Nobuhisa KUMAMOTO et al.

Serial No.: 10/767,439

Filing date: January 30, 2004

For: PROCESS OF PRODUCING
SEMICONDUCTOR CHIP WITH SURFACE
INTERCONNECTION AT BUMP (as amended)

Atty. ref.: AI 318 D1

**INFORMATION
DISCLOSURE
STATEMENT**

November 6, 2007

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is an Information Disclosure Statement submitted under 37 CFR 1.97-1.98, within the time period specified by 37 CFR 1.97(d).

A Form PTO/SB/08 and copies of the references listed therein are attached. Since the references are written in the Japanese language, English-language information about their relevance is also attached. For two of the references, the English-language information is provided in a form of "Patent Abstracts of Japan" summaries. For the remaining reference (JP 10-313074), the English-language information is provided in the form of a counterpart US patent, number 5,977,641.

The references were cited in an Office Action by the Japanese Patent Office on a counterpart Japanese application (that is, on one of the Japanese applications whose priority is claimed in the present US application). A copy of the Japanese Office Action is attached. An English translation of relevant portions thereof is also attached to provide further information about the relevance of the references.

The Japanese Office Action issued on October 16, 2007. Accordingly, the following statement pursuant to 37 CFR 1.97 (e)(1) is appropriate: Each item of information contained

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in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

The \$180 fee specified by 37 CFR 1.17 (p) and required by 37 CFR 1.97 (d)(2) is being submitted concurrently. Should this remittance be accidentally missing or insufficient, though, any fees that may be needed can be charged to our Deposit Account number 18-0002.

It is noted that the US patent attached hereto is not listed on the form PTO/SB/08 because that would be inconsistent with the above statement under 37 CFR 1.97(e)(1); instead, it is attached merely to provide English-language information about the relevance of one of the Japanese-language references.

In view of the foregoing, it is respectfully requested that the references be considered and made of record.

Respectfully submitted,



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AW/ng